IPC ASSOCIATION ELECTRONICS	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute								ials and Mfg Information				
upplier	Information								,					
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
onsemi											2024-05-12			
Contact Na	ame	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-E	Inv-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized	l Representative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-E	Cnv-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type
	FDMF3037 Smart Power		Smart Power Stage	age Module		2024-05-12 MY5		IY5	73.67428		mg	Each		
	cturing Process Inform													
	2 2		Terminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperature			Temperatu		er of Reflow Cyc	eles		
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	second	s 3		
omments														
vel 1 - ma	aximum time at peak tempera	ture during sol	ldering is 10-3	30 seconds										
or more i	nformation regarding materi	al composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, she declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its part is all appliers and the company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appli										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.34295	mg	Supplier	Zinc (Zn)	7440-66-6		0.0076	mg
			Supplier	Iron (Fe)	7439-89-6		0.1522	mg
			Supplier	Copper (Cu)	7440-50-8		6.178	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0051	mg
Die	0.317142	mg	Supplier	Silicon (Si)	7440-21-3		0.3171	mg
Die Attach Solder	2.17762	mg	Supplier	Silver (Ag)	7440-22-4		0.0544	mg
			A	Lead (Pb)	7439-92-1	7a	2.0143	mg
			Supplier	Tin (Sn)	7440-31-5		0.1089	mg
Epoxy	0.1291	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0103	mg
			Supplier	Proprietary	Proprietary Data		0.0116	mg
			Supplier	Bismaleimide	13676-54-5		0.0349	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0013	mg
			Supplier	PTFE	9002-84-0		0.071	mg
Lead Frame	31.0723	mg	Supplier	Silver (Ag)	7440-22-4		1.5538	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0373	mg
			Supplier	Iron (Fe)	7439-89-6		0.7458	mg
			Supplier	Copper (Cu)	7440-50-8		28.7106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	31.2746	mg		Proprietary	proprietary data		2.502	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1564	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.6163	mg
Plating	2.10085	mg	Supplier	Tin (Sn)	7440-31-5		2.1009	mg
Wire Bond - Cu	0.259717	mg	Supplier	Palladium (Pd)	7440-05-3		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2548	mg